

ABSTRACT

To provide a mold release film which has excellent mold releasing property and is capable of reducing contamination of a mold in a sealing step; a process for producing the mold release film; and a process for producing a semiconductor package by using the mold release film. The mold release film 1 is a mold release film to be disposed on a surface of a mold which is to be in contact with a curable resin, in the production of a semiconductor package by disposing a semiconductor element in the mold, and sealing it with the curable resin to form a resin sealed portion. This mold release film 1 comprises a resin-side mold release layer 2 to be in contact with the curable resin at the time of forming the resin sealed portion, and a gas barrier layer 3. The gas barrier layer 3 contains at least one polymer (I) selected from the group consisting of a polymer having vinyl alcohol units and a polymer having vinylidene chloride units, and the thickness of the gas barrier layer 3 is from 0.1 to 5 μm .